



**FH8550M**

**HD Analog CMOS ISP Chip**

**User Datasheet**

Rev: 1.4

2023-11-9



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## Introduction

This document is a brief introduction of FH8550M chip.

## Revision History

Date	Rev	Owner	Description
2017/08/25	V1.1	Hu	Initial
2020-03-12	V1.2	Ryan	Update address
2020-04-21	V1.3	Ryan	Update package overall height and lead width
2023-11-9	V1.4	Ryan	Change pin41 name in Pin Map to be consistent with Pin Arrange

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## 1. Outline

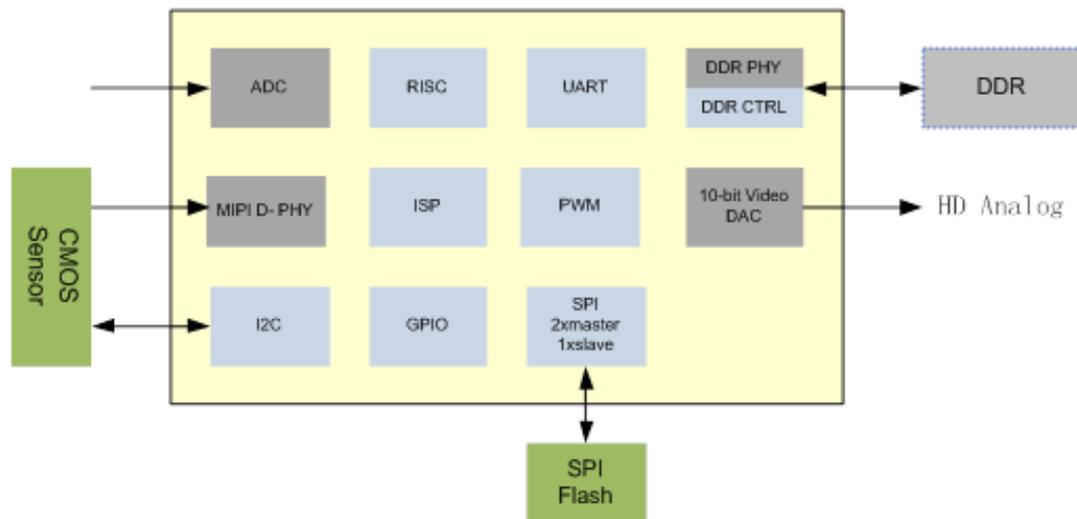
FH8550M is an ISP for CIS (CMOS Image Sensor) and targeted on professional surveillance CCTV camera. FH8550M supports 1M/2M Pixel CIS with MIPI input. It supports high performance image processing technology including 3D de-noise, AF, WDR, and so on. Its video outputs support standard CVBS/960H/1280H and 720P60/50/30/25, 1080P30/25.

### 1.1 Feature

Table 1 Feature

FEATURE	DESCRIPTION		
Support 3D de-noise	<b>Input</b>	Support RGB Bayer	
Support WDR		Support 2M/1.3M/1.0M	
Support AE/AWB/AF		Support MIPI	
Support sensitive areas shielded		Clock effective edge & Frame, Line effective edge is configurable	
Support 720p/1080p HD-Analog output	<b>Output</b>	Standard CVBS/960H/1280H 720p@25fps/30fps/50fps/60fps HD Analog	
Support RS485 Up the Coax function		1080p@25fps/30fps HD Analog	
TOSD	<b>Memory</b>	SPI flash external	
GOSD	<b>Interface</b>	I2C×1 (Master) (Multiplexing)	
DDR Internal		UART×2 (Multiplexing)	
Support LSC		GPIO×28 (Multiplexing)	
Adaptive 2D de-noise		SPI×3 (Master x2,Slave x1) (Multiplexing)	
Y/C de-noise		SADC×3 (Multiplexing)	
Support LTM statistics		PWM×8 (Multiplexing)	
Support move detect		I2S×1 (Multiplexing)	
High performance CFA interpolation		<b>Power</b>	I/O
Support Sensor FPN	Core		1.2v
Support auto bad points detect and delete	DDR		1.8v
Support auto black eliminated	Analog		3.3v
Adaptive Sharpness	<b>Package</b>	QFN68 (8mm×8mm. Pitch=0.4mm)	

## 2. Block Diagram



## 3. Feature

### 3.1 CIS Input

- Support up to 2.0M CMOS sensor
- MIPI Interface
- Clock effective edge & Frame, Line effective edge is configurable

### 3.2 ISP

- Support LSC
- Reduce fixed pattern noise
- Support 3D de-noise
- Adaptive 2D de-noise, support Y/C de-noise
- Support high performance WDR
- Support image information statistics
- Support AE statistics

- Support AWB statistics
- Support AF statistics
- Support LTM statistics
- Support AE/AWB/AF
- Support 256 areas move detect
- Support auto exposure
- High performance CFA interpolation
- Support color correction
- Support Gamma correction, Gamma table is configurable
- Support sensitive areas shielded
- Support OSD
- Video Enhancement: Brightness, sharpness , contrast and saturation adjustment

### **3.3 Video Output**

- Support HD-Analog Output
- Support HD-Analog Output: 1920x1080@25fps/30fps, 1280x720@50fps/60fps
- Support CVBS Output: Standard CVBS, 960H, 1280H
- Support RS485 Up the Coax function

### **3.4 External Interfaces**

- I2C
- 3xSPI, SPI0(master), SPI1(master), SPI2(slave)
- 28 bit GPIO
- 2xUART, UART0 for debug, UART1 for printout
- 3xSAR-ADC
- 8xPWM
- I2S



## 4.1.2 Pin Arrangement

Pin Position	Pin Name	Type	Description
<b>System Signals</b>			
17	CLK_IN	I	27MHz System Clock Input
16	CLK_OUT	O	27MHz System Clock Output
8	RESET	I	System Reset Input, (BANK2 IO POWER DOMAIN) 0: System Reset, 1: Normal Work
40	TEST	I	TEST Mode Select: (Internal Low, BANK1 IO POWER DOMAIN) 0: Normal 1: Test Mode
<b>MIPI Interface</b>			
31	CIS_CLK	O	CIS_CLK (BANK1 IO POWER DOMAIN)
30	CIS_RESET	O	Sensor Reset, Active Low (BANK1 IO POWER DOMAIN)
48	MIPI_CLK_N	O	MIPI_CLK_N (BANK1 IO POWER DOMAIN)
47	MIPI_CLK_P	O	MIPI_CLK_P (BANK1 IO POWER DOMAIN)
42	MIPI_D0_N	O	MIPI_D0_N (BANK1 IO POWER DOMAIN)
43	MIPI_D0_P	O	MIPI_D0_P (BANK1 IO POWER DOMAIN)
44	MIPI_D1_N	O	MIPI_D1_N (BANK1 IO POWER DOMAIN)
45	MIPI_D1_P	O	MIPI_D1_P (BANK1 IO POWER DOMAIN)
51	MIPI_D2_N	O	MIPI_D2_N (BANK1 IO POWER DOMAIN)
50	MIPI_D2_P	O	MIPI_D2_P (BANK1 IO POWER DOMAIN)
53	MIPI_D3_N	O	MIPI_D3_N (BANK1 IO POWER DOMAIN)
52	MIPI_D3_P	O	MIPI_D3_P (BANK1 IO POWER DOMAIN)
46	MIPI_RBIAS	O	MIPI_RBIAS
41	MIPI_VDDA	P	MIPI Power Supply Internal (1.2V)
49	MIPI_VSSA	G	MIPI Ground
<b>GPIO</b>			
2	GPIO_0	I, O	GPIO (BANK2 IO POWER DOMAIN)
3	GPIO_1	I, O	GPIO (BANK2 IO POWER DOMAIN)
21	GPIO_2	I, O	GPIO (BANK2 IO POWER DOMAIN)
22	GPIO_3	I, O	GPIO (BANK2 IO POWER DOMAIN)
4	GPIO_4	I, O	GPIO (BANK2 IO POWER DOMAIN)
5	GPIO_5	I, O	GPIO (BANK2 IO POWER DOMAIN)
6	GPIO_6	I, O	GPIO (BANK2 IO POWER DOMAIN)
7	GPIO_7	I, O	GPIO (BANK2 IO POWER DOMAIN)
19	GPIO_8	I, O	GPIO (BANK2 IO POWER DOMAIN)
20	GPIO_9	I, O	GPIO (BANK2 IO POWER DOMAIN)
12	GPIO_11	I, O	GPIO (BANK2 IO POWER DOMAIN)

13	GPIO_14	I、O	GPIO (BANK2 IO POWER DOMAIN)
14	GPIO_15	I、O	GPIO (BANK2 IO POWER DOMAIN)
15	GPIO_16	I、O	GPIO (BANK2 IO POWER DOMAIN)
23	GPIO_17	I、O	GPIO (BANK2 IO POWER DOMAIN)
24	GPIO_18	I、O	GPIO (BANK2 IO POWER DOMAIN)
25	GPIO_19	I、O	GPIO (BANK2 IO POWER DOMAIN)
26	GPIO_20	I、O	GPIO (BANK2 IO POWER DOMAIN)
27	GPIO_21	I、O	GPIO (BANK2 IO POWER DOMAIN)
28	GPIO_22	I、O	GPIO (BANK2 IO POWER DOMAIN)
65	GPIO_23	I、O	GPIO (BANK2 IO POWER DOMAIN)
34	GPIO_24	I、O	GPIO (BANK1 IO POWER DOMAIN)
36	GPIO_25	I、O	GPIO (BANK1 IO POWER DOMAIN)
68	GPIO_30	I、O	GPIO (BANK2 IO POWER DOMAIN)
1	GPIO_31	I、O	GPIO (BANK2 IO POWER DOMAIN)
I2C			
32	CIS_SCL	O	I2C CLK (BANK1 IO POWER DOMAIN)
33	CIS_SDA	I、O	I2C DATA (BANK1 IO POWER DOMAIN)
DAC			
56	DAC_COMP	I、A	Video DAC Compensation Input
54	DAC_CVBS	O、A	Video DAC Video DAC Video Output
57	DAC_REXT	I、A	Video DAC Configuration Resistance
55	DAC_VDDA	P、A	Video DAC Power Supply (3.3V, connect with SDAC_VDDA internal)
SADC			
60	SADC_CH0	I、A	SADC CH0 Input
61	SADC_CH1	I、A	SADC CH1 Input
62	SADC_CH2	I、A	SADC CH2 Input
58	SADC_VDDA	P、A	SADC Power Supply (3.3V, connect with DAC_VDDA internal)
59	SADC_VSSA	P、A	SADC Ground
PLL			
63	PLL_VDDA	P	PLL Power Supply Internal (1.2V)
64	PLL_VSSA	G	PLL Ground
Power / Ground			
9、10、37、38	DDRIO_18	P	DDR Power Supply (1.8V)
11、29、66、39	VDDK	P	Core Power Supply (1.2V)
35	VDDIO_BANK1	P	BANK1 IO Power Supply (1.8V or 3.3V)
18、67	VDDIO_BANK2	P	BANK2 IO Power Supply (3.3V)

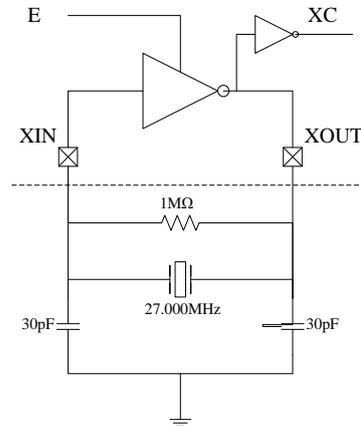
### 4.1.3 GPIO Descriptions

GPIO	Name	Direction	PU/PD	Description
0	FPN	I	U	1:Normal; 0:FPN
	UART0_TX	O		UART Interface
1	UART0_RX	I	U	
2	BOOT_SEL0	I	D	BOOT_SEL0 Default (with pull down resistor internal)  {BOOT_SEL1, BOOT_SEL0} =00, SPI Flash normal work  {BOOT_SEL1, BOOT_SEL0} =01, SPI slave mode  {BOOT_SEL1, BOOT_SEL0} =1x, Xmodem update mode
	PWM0	O		Multiplexing: PWM0
3	BOOT_SEL1	I	D	BOOT_SEL1 Default (with pull down resistor internal)
	PWM1	O		Multiplexing: PWM1
4	GPIO_4	O	U	GPIO
	SPI0_CS	O		SPI0_CS
	SPI2_CS	O		SPI2_CS
5	SPI0_CLK	O	D	SPI0_CLK
	SPI2_CLK	O		SPI2_CLK
6	SPI0_TXD	O	D	SPI0_TXD
	SPI2_TXD	O		SPI2_TXD
7	SPI0_RXD	I	D	SPI0_RXD
	SPI2_RXD	I		SPI2_RXD
8	IRCUT_OFF	O	U	IRCUT_OFF
9	IRCUT_ON	O	U	IRCUT_ON
10	CIS Rst	O	U	CIS_RSTn for Sensor (with pull up resistor internal)
11	Day/Night	I	U	DAY/NIGHT Selection Default (with pull up resistor internal) 0 → Night (Black and White)  1 → Day (Colour)
	I2S_CLK	O		Multiplexing: I2S_CLK
12	CIS_SDA	I/O		I2C
13	CIS_SCL	I/O		
14	CVBS_HD_Sel0	I	U	HD_SEL0 Default (with pull up resistor internal)

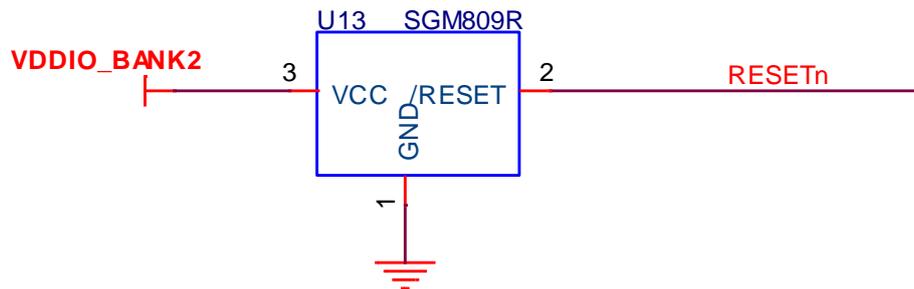
				{HD_SEL1, HD_SEL0} =00, CVBS output; Others HD output
	I2S_WS	O		Multiplexing: I2S_WS
15	CVBS_HD_Sel1			HD_SEL1 Default (with pull up resistor internal)
	I2S_TXD	O		Multiplexing: I2S_TXD
16	Fmt_Sel	I	U	FMT_SEL Default (with pull up resistor internal) CVBS : 0 → NTSC, 1 → PAL HD: 0 → 30fps, 1 → 25fps
	I2S_RXD	I	U	Multiplexing: I2S_RXD
17	PWM2	O	U	PWM2 (with pull up resistor internal)
	I2S_MCLK	O		Multiplexing: I2S_MCLK
	AVE_DEBUG	O		AVE debug for Test
18	SPI1_CS0	O	U	SPI1_CS0 (with pull up resistor internal)
	PWM3	O		Multiplexing: PWM3
19	SPI1_CS1	O	U	SPI1_CS1 (with pull up resistor internal)
	PWM4	O		Multiplexing: PWM4
20	SPI1_CLK	O	U	SPI1_CLK (with pull up resistor internal)
	PWM5	O		Multiplexing: PWM5
21	SPI1_TXD	O	U	SPI1_TXD (with pull up resistor internal)
	PWM6	O		Multiplexing: PWM6
22	SPI1_RXD	O	U	SPI1_RXD (with pull up resistor internal)
	PWM7	O		Multiplexing: PWM7
23	RX485_RX	I	U	RS485 Input
24	GPIO_24	O	D	GPIO
25	GPIO_25	O	D	GPIO
30	UART1_TX	O	U	UART1 TX
31	UART1_RX	I	U	UART1 RX

## 4.2 Reference Circuit

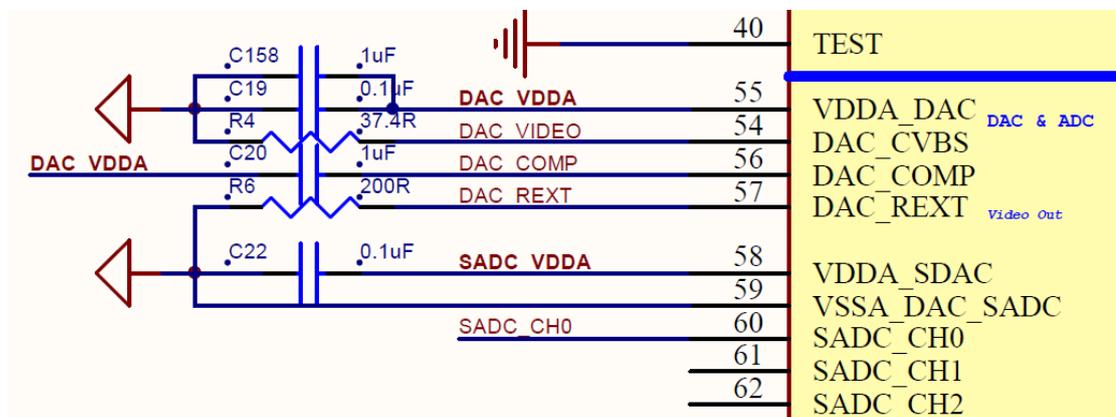
### 4.2.1 OSC Reference Circuit



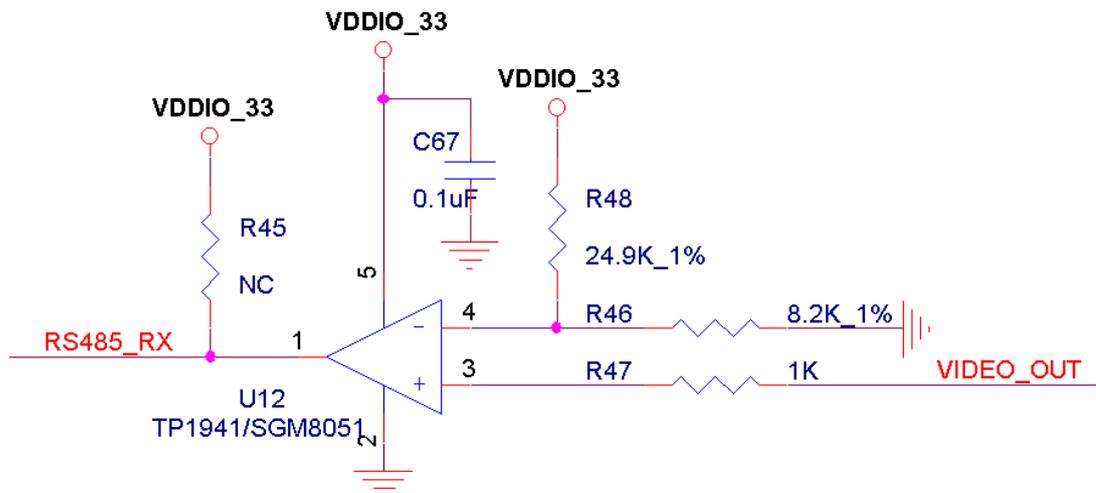
### 4.2.2 Reset Reference Circuit



### 4.2.3 DAC Reference Circuit



## 4.2.4 RS485 Reference Circuit



## 5. DC Electrical Specifications

### 5.1 Power Supply Specifications

Power Type	Description	Min	Type	Max	Unit
VDDK	Core Power	TBD	230	TBD	mA
DAC/ADC_VDDA	DAC/ADC Power	TBD	54	TBD	mA
VDDIO_BANK1	IO_BANK1 Power	TBD	1	TBD	mA
VDDIO_BANK2	IO_BANK2 Power	TBD	9	TBD	mA
DDRIO_18	DDR Power	TBD	56	TBD	mA

### 5.2 Working Conditions

Symbol	Parameter	Min	Type	Max	Unit
VDDK	Core Power	TBD	1.20	TBD	V
DAC/ADC_VDDA	DAC/ADC Power	TBD	3.30	TBD	V
VDDIO_BANK1	IO_BANK1 Power	TBD	3.30	TBD	V
		TBD	1.80	TBD	V

VDDIO_BANK2	IO_BANK2 Power	TBD	3.30	TBD	V
DDRIO_18	DDR Power	TBD	1.80	TBD	V

### 5.3 I/O Specifications

Symbol	Parameter	Min.	Norm	Max
VDD33	I/O supply voltage	2.97V	3.3V	3.63V
V <sub>IH</sub>	Input High Voltage	2.0V		VDD33+0.3V
V <sub>IL</sub>	Input Low Voltage	-0.3V		0.8V
V <sub>T</sub>	Threshold point	1.30V	1.41V	1.53V
V <sub>T+</sub>	Schmitt trig Low to High threshold point	1.54V	1.64V	1.74V
V <sub>T-</sub>	Schmitt trig. High to Low threshold point	0.95V	1.02V	1.09V
T <sub>J</sub>	Junction Temperature	0 °C	25°C	125°C
I <sub>L</sub>	Input Leakage Current			±1uA
I <sub>OZ</sub>	Tri-State output leakage current			±1uA
R <sub>PU</sub>	Pull-up Resistor	62kohm	77kohm	112kohm
R <sub>PD</sub>	Pull-down Resistor	58kohm	81kohm	157kohm
V <sub>OL</sub>	Output low voltage @ I <sub>OL</sub> =2,4...24mA			0.4V
V <sub>OH</sub>	Output high voltage @ I <sub>OH</sub> =2,4...24mA	2.4V		
I <sub>OL</sub>	Low level output current @ V <sub>OL</sub> =0.4V			
		4mA	4.2mA	6.6mA
I <sub>OH</sub>	High level output current @ V <sub>OH</sub> =2.4V			
		4mA	4.7mA	9.6mA

Symbol	Parameter	Min.	Norm	Max	
VDD33	I/O supply voltage	1.62V	1.8V	1.98V	
V <sub>IH</sub>	Input High Voltage	0.65*		VDD33+ 0.3V	
V <sub>IL</sub>	Input Low Voltage	-0.3V		0.35* VDD33	
V <sub>T</sub>	Threshold point	0.76V	0.82V	0.87V	
V <sub>T+</sub>	Schmitt trig Low to High threshold point	0.95V	1.04V	1.09V	
V <sub>T-</sub>	Schmitt trig. High to Low threshold point	0.55V	0.59V	0.62V	
T <sub>J</sub>	Junction Temperature	0 °C	25 °C	125 °C	
I <sub>L</sub>	Input Leakage Current			± 1uA	
I <sub>OZ</sub>	Tri-State output leakage current			± 1uA	
R <sub>PU</sub>	Pull-up Resistor	123kohm	174kohm	276kohm	
R <sub>PD</sub>	Pull-down Resistor	126kohm	202kohm	416kohm	
V <sub>OL</sub>	Output low voltage @ I <sub>OL</sub> =2,4...24mA			0.45V	
V <sub>OH</sub>	Output high voltage @ I <sub>OH</sub> =2,4...24mA	VDD33- 0.45V			
I <sub>OL</sub>	Low level output current @ V <sub>OL</sub> =0.45V				
		4mA	2.0mA	3.7mA	5.3mA
I <sub>OH</sub>	High level output current @ V <sub>OH</sub> =VDD33-0.45V				
		4mA	1.8mA	3.0mA	4.2mA

## 5.4 Power up Sequence

The digital and analog supply voltages can be powered in any order, on the basis of system reset time keep **TBD ms** at least.

## 5.5 PLL Specifications

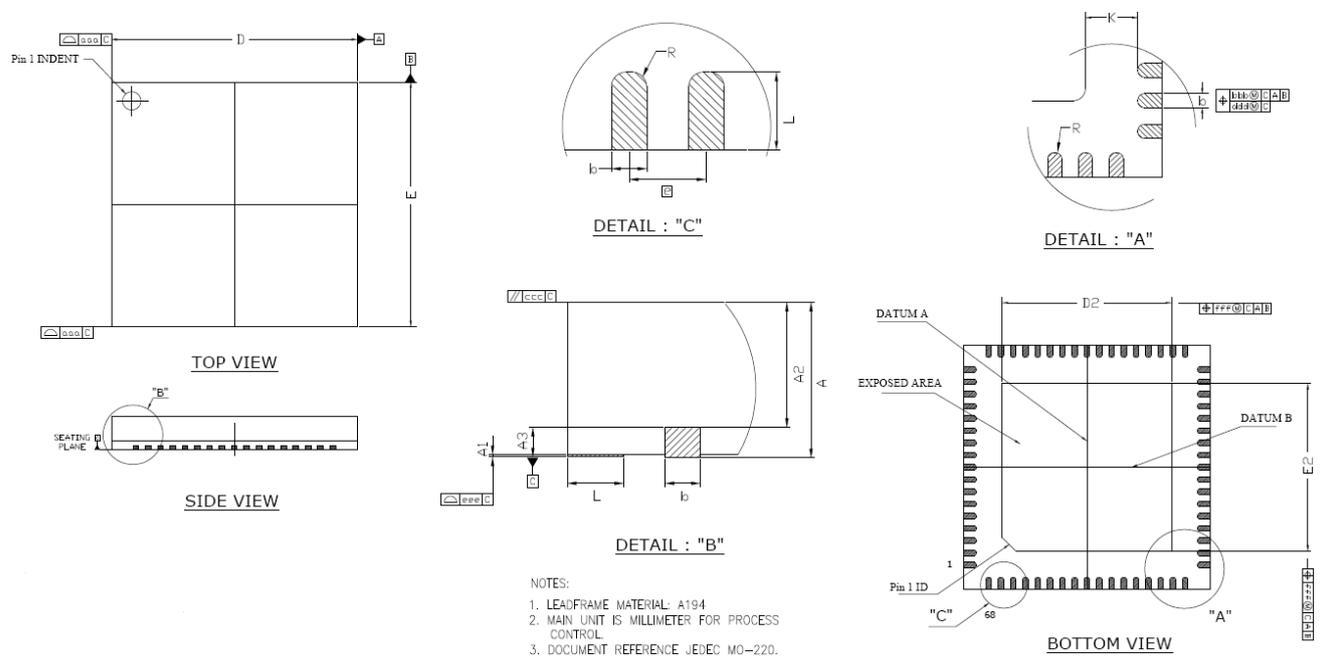
Parameter	Symbol	Min	Typ	Max	Unit	Condition
Input clock frequency	XIN/N	1	-	50	MHz	
VCO frequency	VOUT	500	-	1500	MHz	
Output clock frequency	CLK_OUT	62.5	-	1500	MHz	
Period jitter	RMS	-	12	-	ps	VCO freq = 960 MHz; Clean Power
	PK_PK	-	80	-	ps	Temp=25 °C·TT,1.2V
Duty cycle	--	40	50	60	%	VCO freq = 500 ~1500 MHz

## 6. Temperature Specifications

FH8550M Operating Temperature:  $-20^{\circ}\text{C} \sim +70^{\circ}\text{C}$ 。

## 7. Package

The chip package is QFN68. Its body size is 8.00mm x 8.00mm x 0.85mm. The following figure shows the package and the dimensions of the FH8550M.



Dimension Matrix:

SYMBOL:	UNIT & DIMENSION:		DIMENSION UNIT:MM		
	MIN	NOM	MAX		
ⓐ (LEAD PITCH):	0.400 BSC				
D,E (PKG SIZE):	7.900	8.000	8.100		
D1,E1 (CAVITY WIDTH(X)):	--				
L (LEAD LENGTH):	0.350	0.400	0.450		
N (LEAD COUNT):	--	68.000	--		
A (OVERALL HEIGHT):	0.800	0.850	0.900		
A1 (STANDOFF):	--	--	0.050		
A2 (MOLD HEIGHT):	--	0.650	--		
A3 (L/F THICKNESS):	0.203 REF				
R (LEAD R-FILLET):	--	0.075	--		
b (LEAD WIDTH):	0.150	0.200	0.250		
K (TIP TO EXPOSED PAD EDGE):	0.200	--	--		
θ (DRAFT ANGLE):	--	--	--		

TOLERANCE OF FORM & POSITION:			
UNIT: MM			
	MIN	NOM	MAX
aaa	--	--	0.100
bbb	--	--	0.070
ccc	--	--	0.200
ddd	--	--	0.050
eee	--	--	0.080
fff	--	--	0.100

L/F	D2 , E2 (EXPOSED PAD SIZE):		
	DIMENSION UNIT:MM		
	MIN	NOM	MAX
(1.)	5.400	5.500	5.600

## 8. Boot Select

The following table provides three boot modes which FH8550M supports. It depends on the status of GPIO\_2 and GPIO\_3 during power up stage.

Table 2 Boot Select

GPIO	GPIO_3=0	GPIO_3=1
GPIO_2=0	SPI Master Mode	Xmodem Mode
GPIO_2=1	SPI Slave Mode	Xmodem Mode

- SPI Master mode: normal work, boot from SPI Flash.
- SPI Slave mode: work as SPI slave mode.
- Xmodem mode: update mode, down the code from PC to SPI Flash or DDR by UART0.